

C-CONTAINING SPUTTERING TARGET AND METHOD FOR PRODUCING SAME

ABSTRACT

A sputtering target with suppressed aggregation of C particles and reduced generation of particles is provided.

A C-containing sputtering target comprises Pt, C, and one or more selected from Fe and Co, where in a particle size distribution of a dissolution residue of the sputtering target, 90 percentile of the particle diameter based on the volume, D90 is 20.0 μm or less, and particle size of less than 1.0 μm accounts for 40% or less in cumulative volume distribution.